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(12) **United States Design Patent**  
**Sohn et al.**

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- (54) **SEMICONDUCTOR DEVICE**
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(Continued)

(\*\*) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/110, 182, 184; 361/713, 728, 736,  
361/760, 761, 775, 679.01, 820; 257/666,  
257/668, 678, 684, 690; 324/71.5, 252;  
174/250, 253; 438/64, 656, 66  
See application file for complete search history.

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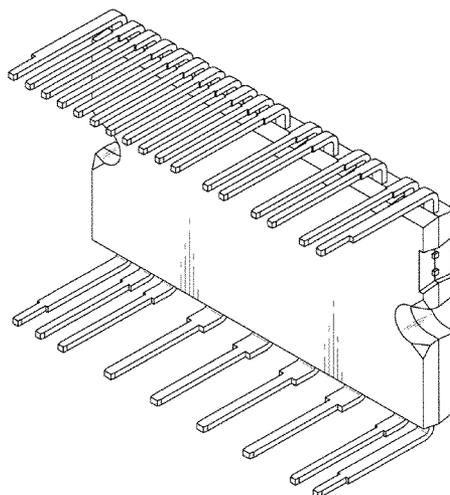
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a semiconductor device showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a left side view thereof;  
FIG. 5 is a right side view thereof;  
FIG. 6 is a top plan view thereof; and,  
FIG. 7 is a bottom plan view thereof.

**1 Claim, 4 Drawing Sheets**



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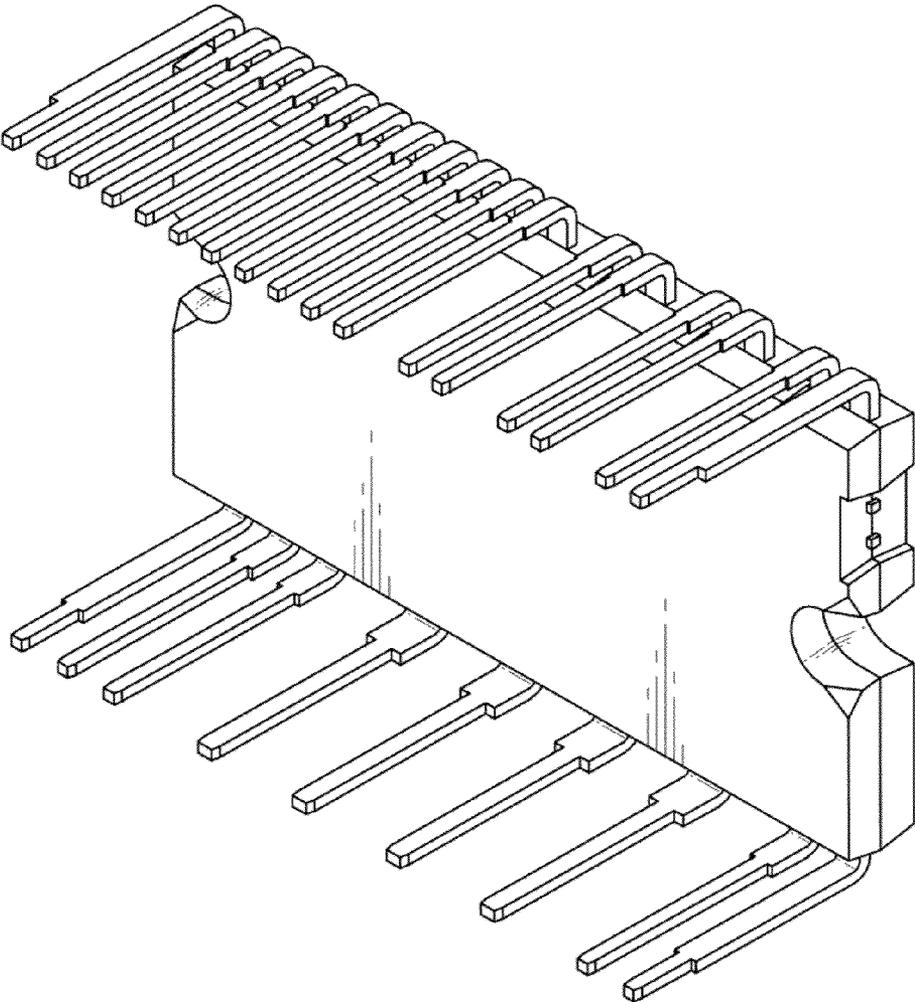


FIG. 1

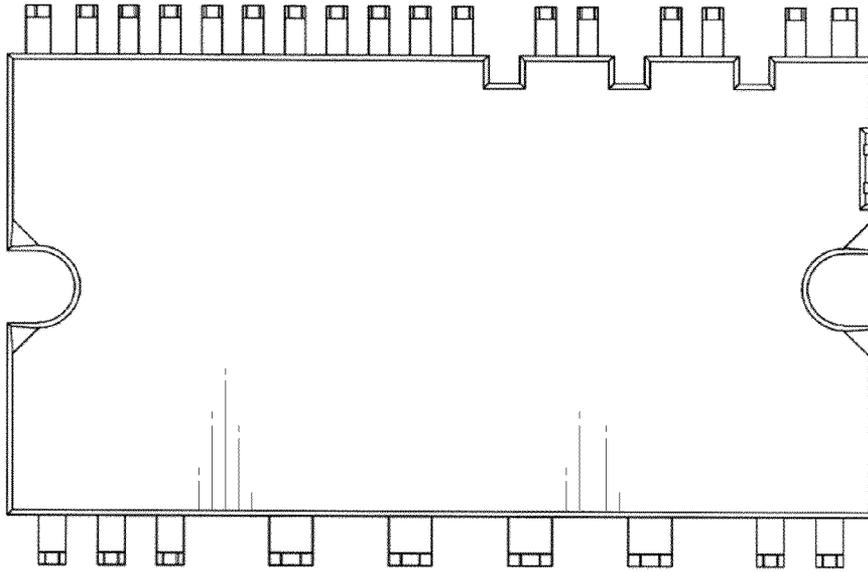


FIG. 2

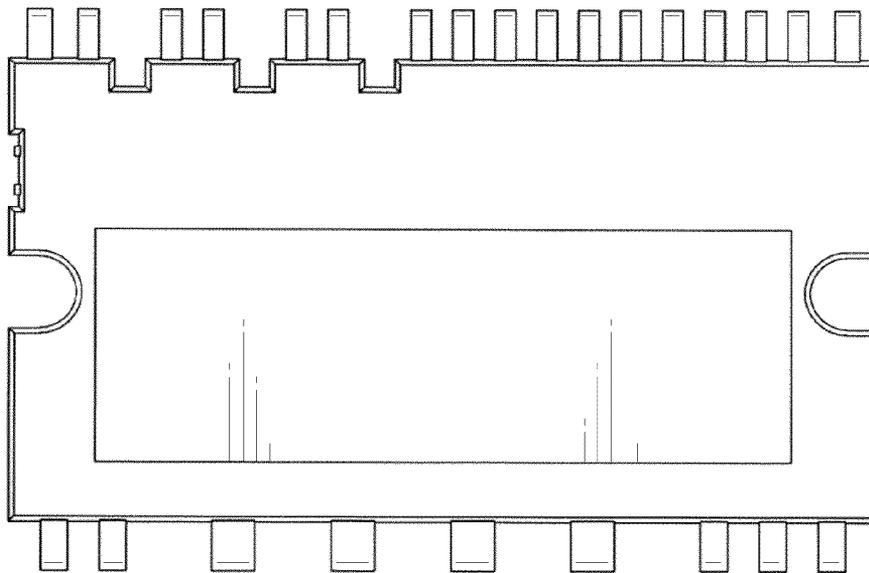


FIG. 3

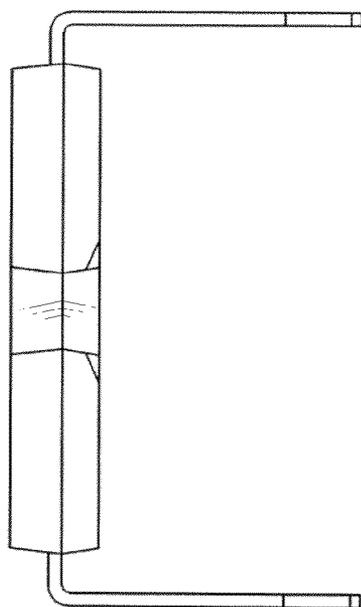


FIG. 4

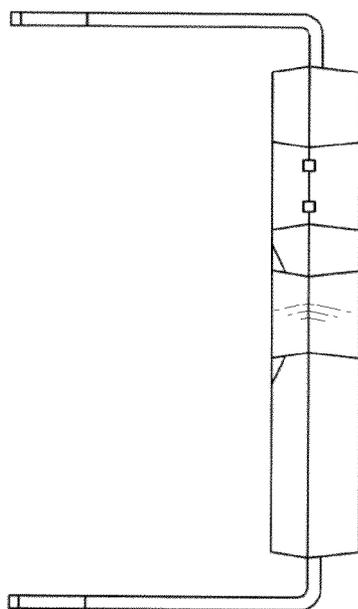


FIG. 5

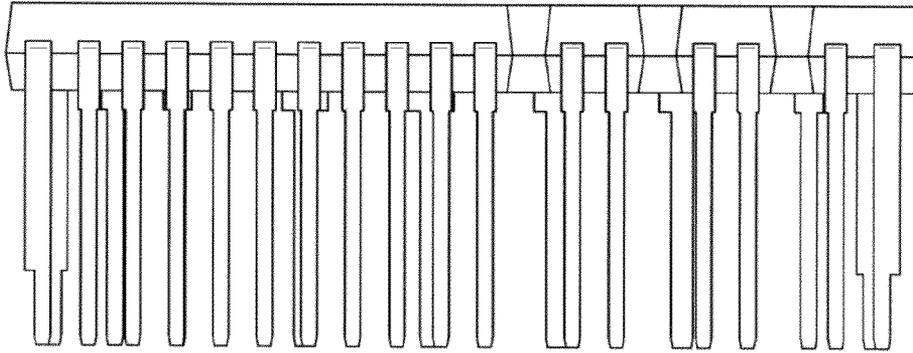


FIG. 6

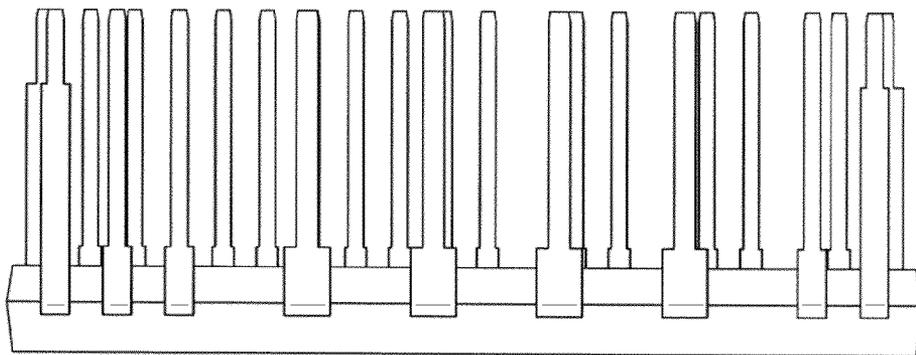


FIG. 7